

- NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.
- 2 CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A=>SIGNAL CONTACT=>MF CONTACT B) WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.
- 3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)
- 4 IT SHOWS THE VACUUM PICKUP AREA. (SEE PAGE 2) REMOVE THE MYLAR TAPE BEFORE MATING CONNECTORS.
- 5 THIS IS PACKAGED IN TRAY. (50pcs/TRAY)
- 6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.
- 7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
3	PHOSPHOR BRONZE		CONTACT AREA:GOLD 0.1 μm LEAD AREA:GOLD 0.03 μm UNDER PLATING:NICKEL 1.3 μm	5	COPPER ALLOY		CONTACT AREA:GOLD 0.1 μm LEAD AREA:TIN-PLATING 1 μm UNDER PLATING:NICKEL 1.3 μm
2	POLYAMIDE	BLACK	UL94V-0	4	COPPER ALLOY		CONTACT AREA:GOLD 0.1 μm LEAD AREA:TIN-PLATING 1 μm UNDER PLATING:NICKEL 1.3 μm
1	POLYAMIDE	BLACK	UL94V-0				
7	POLYIMIDE						
6	POLYSTYRENE						

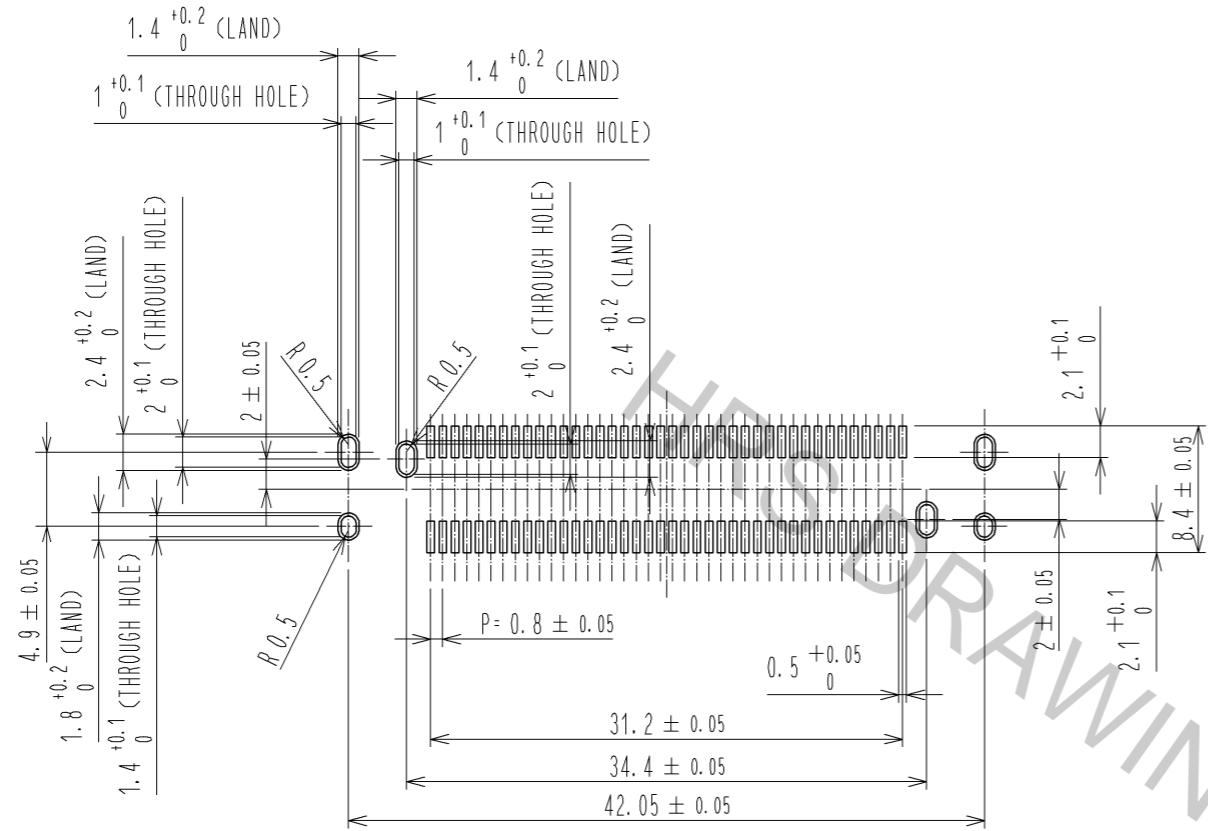
  

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	2 : 1	△	APPROVED : HS. OKAWA 11.08.24 CHECKED : KI. HIROKAWA 11.08.24 DESIGNED : TH. SANO 11.08.24 DRAWN : TH. SANO 11.08.24			

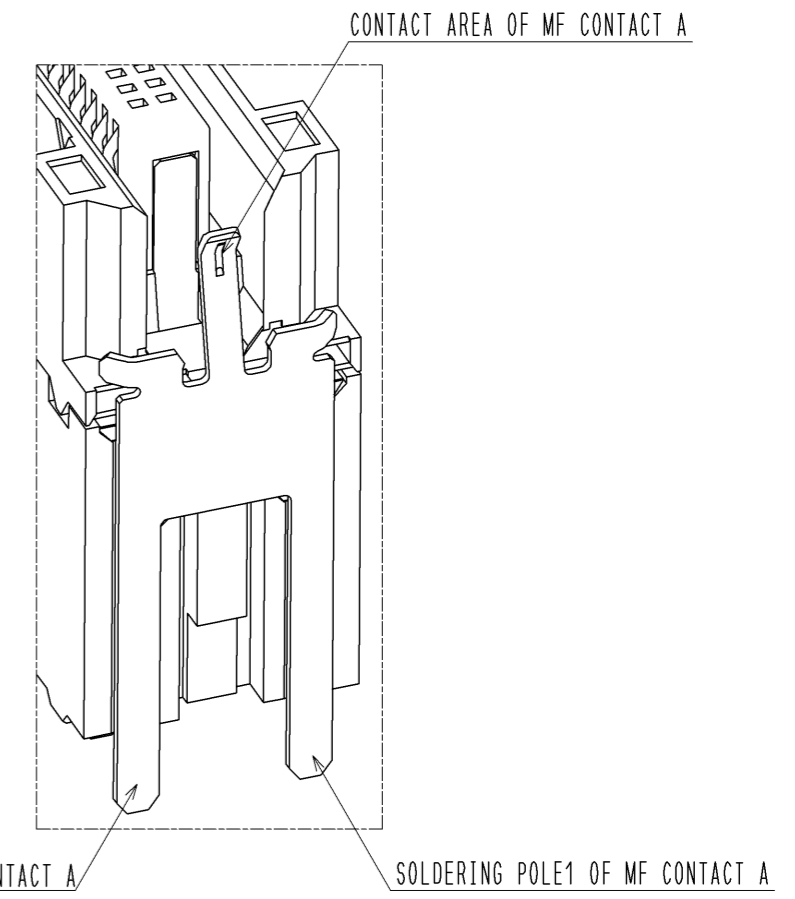
DRAWING NO.	PART NO.	CODE NO.
EDC3-334392-00	FX18-80S-0.8SV20	CL579-0032-6-00

RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)  
 (PCB THICKNESS:t=1.6mm METAL MASK THICKNESS:t=0.12mm)

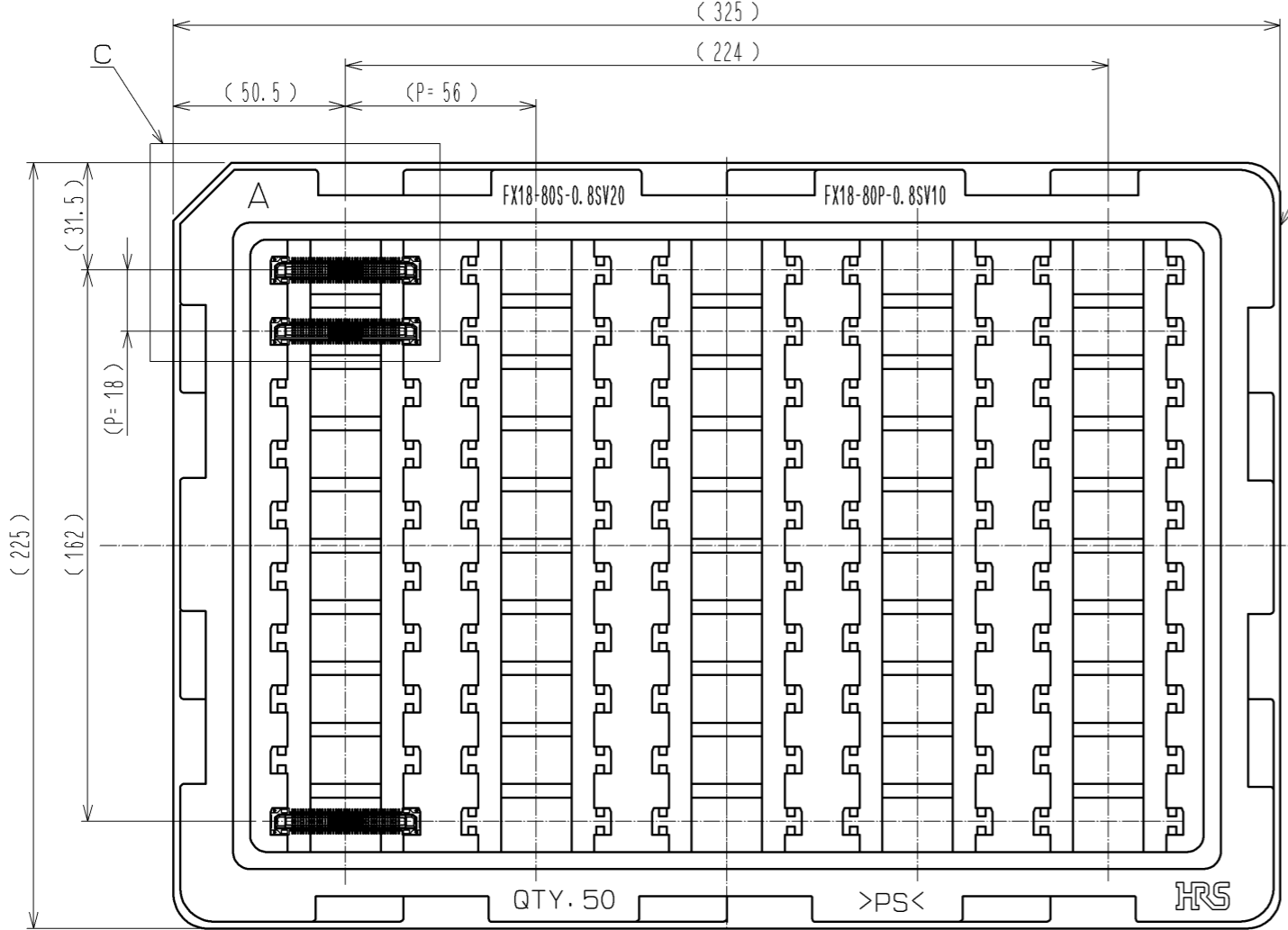


5 DRAWING FOR PACKING(1:2)

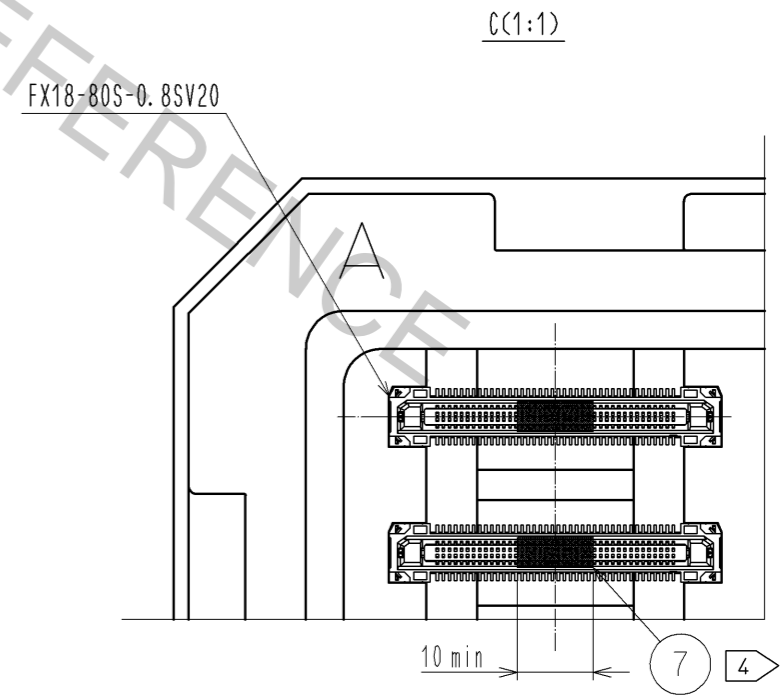
8 CONFIGURATION OF MF CONTACT A



NOTE 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES. BE SURE TO CONNECT TO THE SAME CIRCUIT.



6



<b>HRS</b>	DRAWING NO.	EDC3-334392-00	2/2
	PART NO.	FX18-80S-0.8SV20	
	CODE NO.	CL579-0032-6-00	